

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S13	864	(257/432-434).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/24 19:49
S14	193	(257/432-434).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/24 19:51
S15	3008	(257/678 or 257/680).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/24 19:51
S16	84	(257/678 or 257/680).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/24 19:54
S17	10	(257/796).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/24 19:54
S18	1033	(257/432-434).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:49
S19	225	(257/432-434).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:51
S20	3570	(257/678 or 257/680).ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:51

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S21	1275	(257/678 or 257/680).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and (encapsul\$5 or resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:52
S22	105	(257/678 or 257/680).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:54
S23	353	(257/796).ccls. and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) and (encapsul\$5 or resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:55
S24	688	semiconductor and ((base or frame or substrate) same ((groove or recess or cavity) with adhesion))	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2006/05/24 19:56
S25	455	semiconductor and optoelectronic and ((encapsul\$5 or resin) with (transparent or translucent))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:57
S26	280	semiconductor and optoelectronic and ((encapsul\$6 or resin) with (transparent or translucent)) and ((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:58
S27	43	semiconductor and optoelectronic and ((encapsul\$6 or resin) with (transparent or translucent)) and (((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) same (groove or wing or cavity or recess\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/24 19:58
S28	37	semiconductor and optoelectronic and ((encapsul\$6 or resin) with (transparent or translucent)) and (((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) same (groove or wing or cavity or recess\$3)) and @ad<"20040129"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/25 06:05

## EAST Search History

S29	7241	semiconductor and (encapsul\$6 or resin) and (((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) same (groove or wing or cavity or recess\$3)) and @ad<"20040129"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/25 06:06
S30	1438	semiconductor and ((encapsul\$6 or resin) same (((base or frame or substrate) with (metal or copper or cu or Al or aluminum or conductive)) with (groove or wing or cavity or recess\$3))) and @ad<"20040129"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/25 06:07